

In the Claims:

Please amend the claims as follows:

Claims

What is claimed is:

1. (Amended) A process ~~Process~~ for producing a metal-ceramic substrate, ~~especially copper ceramic substrate~~, in which ~~(process)~~ at least one metal foil ~~(3', 4')~~ at a time is applied to ~~the~~ a surface sides of a ceramic layer or a ceramic substrate ~~(2)~~ using a high temperature bonding process and the metal foil ~~(3, 4)~~ is structured on at least one surface side for forming conductive tracks, contact surfaces, ~~and the like, characterized in that~~ wherein after the high temperature bonding process at least one coating ~~(5)~~ of a brazing resist is applied to the metal surface of the at least one metal foil ~~(3', 4')~~ or the at least one metal coating ~~(3, 4, 3', 4')~~.

2. (Amended) The process ~~Process~~ as claimed in claim 1, wherein high temperature bonding is carried out at a temperature greater than 650°C.

3. (Amended) A process ~~Process~~ as claimed in claim 1 ~~or 2~~, wherein high temperature bonding is a direct bonding process.

4. (Amended) A process ~~Process~~ as claimed in ~~one of the preceding claims~~ claim 1, wherein high temperature bonding is an active brazing process.

5. (Amended) A process ~~Process~~ as claimed in ~~one of the preceding claims~~ claim 1, wherein at least one coating ~~(5)~~ of brazing resist is applied before structuring.

6. (Amended) A process ~~Process~~ as claimed in ~~one of the preceding claims~~ claim 1, wherein at least one coating ~~(5)~~ of brazing resist is applied after structuring.

7. (Amended) A process ~~Process~~ as claimed in ~~one of the preceding claims~~ claim 1, wherein the metal foils are copper

foils and they are provided on the ceramic substrate ~~(2)~~ by means of the DCB process or the active brazing process.

8. (Amended) A process ~~Process~~ as claimed in ~~one of the preceding claims~~ claim 1, wherein structuring of ~~the~~ at least one metal foil ~~(3', 4')~~ takes place by means of masking-etching process and wherein ~~the~~ at least one coating (5) of brazing resist is applied immediately after this structuring.

9. (Amended) A process ~~Process~~ as claimed in ~~one of the preceding claims~~ claim 1, wherein structuring of ~~the~~ at least one metal foil ~~(3', 4')~~ takes place by means of a masking-etching process using an etching resist and wherein ~~the~~ at least one coating ~~(5)~~ of brazing resist is applied immediately before application of the etching resist.

10. (Amended) A process ~~Process~~ as claimed in ~~one of the preceding claims~~ claim 1, wherein after applying the brazing resist coating ~~(5)~~ the metal of the metal coating is removed at least in the surface areas bordering this brazing resist coating ~~(5)~~.

11. (Amended) A process ~~Process~~ as claimed in claim 10, wherein removal takes place by etching, ~~for example~~ using hydrogen peroxide, sodium persulfate, copper chloride or iron chloride.

12. (Amended) A process ~~Process~~ as claimed in claim 10 ~~or 11~~, wherein removal takes place with a thickness from 0.1 to 20 microns.

13. (Amended) A process ~~Process~~ as claimed in ~~one of the preceding claims~~ claim 1, wherein before ~~the~~ application of at least one brazing resist coating ~~(5)~~ cleaning of the metal surfaces, ~~preferably~~ by removing a surface area of the metal coatings, takes place.

14. (Amended) A process ~~Process~~ as claimed in claim 13, wherein cleaning takes place by chemical removal and/or by plasma etching and/or by electrical etching and/or galvanic removal and/or by mechanical working, ~~for example~~ by brushing or grinding.

15. (Amended) A process ~~Process~~ as claimed in claim 14, wherein chemical cleaning takes place using a hydrogen peroxide solution or a sodium persulfate solution.

16. (Amended) A process ~~Process~~ as claimed ~~in one of the preceding claims~~ claim 1, wherein a surface metal coating ~~(10)~~ is applied to at least one surface area ~~(8)~~ of the at least one metal coating, which area is produced ~~preferably~~ by removal and adjoins at least one brazing resist coating ~~(5)~~.

17. (Amended) A process ~~Process~~ as claimed in claim 16, wherein the surface metal coating ~~(10)~~ is applied such that the surface which has been formed by this surface metal coating is level or roughly level with the surface of at least one brazing resist coating ~~(5)~~ or level or roughly level with the untreated surface underneath at least one brazing resist coating ~~(5)~~.

18. (Amended) A process ~~Process~~ as claimed in claim 16, wherein the surface metal coating ~~(10)~~ is applied such that the surface which has been formed by this surface metal coating projects over the surface level of at least one brazing resist coating ~~(5)~~ or over the surface level of the untreated surface underneath at least one brazing resist coating ~~(5)~~.

19. (Amended) A process ~~Process~~ as claimed in claim 16, wherein the surface metal coating ~~(10)~~ is applied such that the surface which has been formed by this surface metal coating is somewhat lower than the surface level of at least one brazing resist coating ~~(5)~~ or of the untreated surface underneath at least one brazing resist coating ~~(5)~~.

20. (Amended) A process ~~Process~~ as claimed in ~~one of the preceding claims~~ claim 1, wherein an epoxide-based resist is used for the brazing resist coating and wherein the brazing resist coating cures thermally.

21. (Amended) A process ~~Process~~ as claimed in ~~one of the preceding claims~~ claim 1, wherein at least one brazing resist coating has a thickness of 0.5 to 100 microns.

22. (Amended) A process ~~Process~~ as claimed in ~~one of the preceding claims~~ claim 1, wherein at least one brazing resist coating ~~(5)~~ is structured in an area ~~(5')~~ for forming an optically readable code.